

Schottky Barrier Diode DB3X317K0L

DB3X317K0L Silicon epitaxial planar type

For high frequency rectification

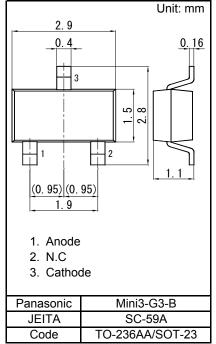
- Features
- Low forward voltage VF ٠
- Forward current (Average) IF(AV) = 1 A rectification is possible
- Halogen-free / RoHS compliant ٠ (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: 5R

Packaging

Reverse voltage

Junction temperature

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)



 $\square$ 

С			
Symbol	Rating	Unit	
VR	30	V	Internal Connection
VRRM	30	V	
IF(AV)	1	А	3
IFSM	5	А	
Tj	125	°C	
Topr	-40 to +85	°C	

°C

#### Absolute Maximum Ratings Ta = 25 °C

Parameter

Non-repetitive peak forward surge current

Repctitive peak reverse voltage Forward current (Average)

Operating ambient temperature

Storage temperature		Tstg	-55 to +125				
Note:	*1	50 Hz sine wave 1 cycle (Non-repetit	ne wave 1 cycle (Non-repetitive peak current)				

# **Panasonic**

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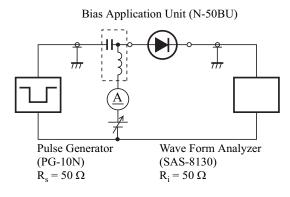
#### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

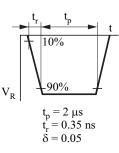
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF1	IF = 700 mA		0.41	0.48	V
Forward voltage	VF2	IF = 1 A		0.46	0.52	V
Reverse current	IR	VR = 30 V		10	100	μA
Terminal capacitance	Ct	VR = 10 V, f = 1 MHz		22		pF
Deverse receiver times *1	trr	IF = IR = 100 mA	7.8		ns	
Reverse recovery time <sup>1</sup>		Irr = 0.1 × IR, RL = 100 Ω		7.0		115

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

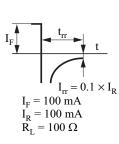
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. \*1 trr test circuit





Input Pulse



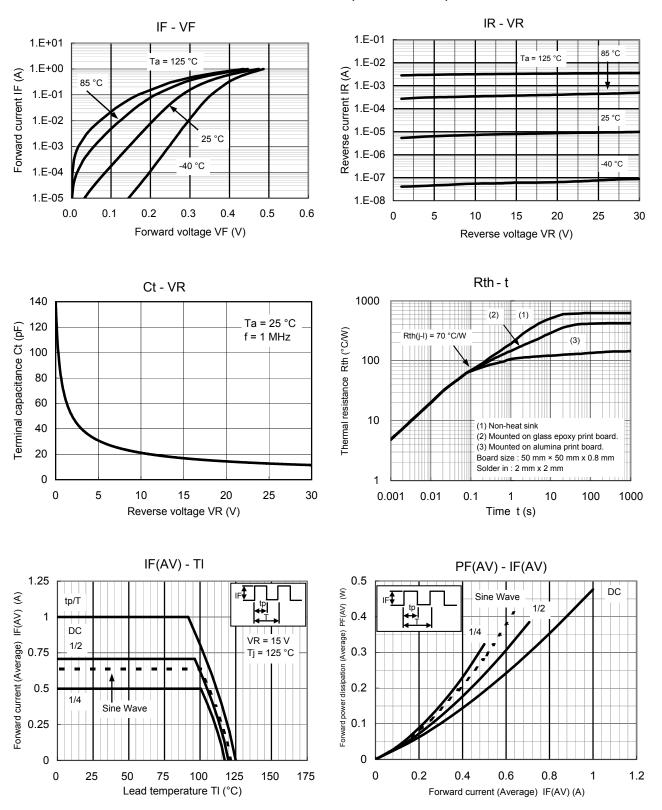
Output Pulse

Established : 2010-03-29 Revised : 2013-04-26





Technical Data (reference)



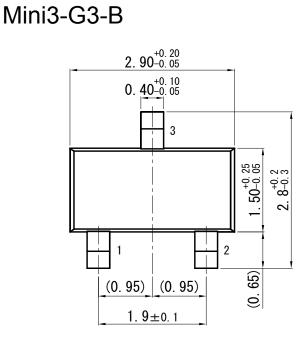
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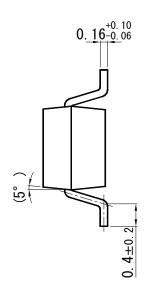
Established : 2010-03-29 Revised : 2013-04-26

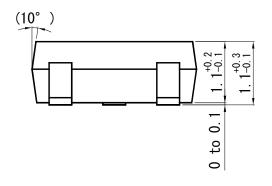


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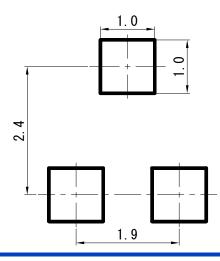
Unit: mm







Land Pattern (Reference) (Unit: mm)



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